

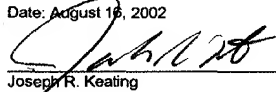


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Date: August 16, 2002

  
Joseph R. Keating

2834  
#15/C  
REVIEWS  
8.30.02  
  
PATENT  
36856.345

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Masaya WAJIMA et al.

Serial No.: 09/656,106

Filed: September 6, 2000

Title: CHIP ELECTRONIC COMPONENT  
AND MOUNTING STRUCTURE OF THE  
SAME

Art Unit: 2834

Examiner: J. Gonzalez

**AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated May 16, 2002, please amend the above-identified patent application as follows:

**IN THE CLAIMS:**

Please replace claims 1, 9, 13 and 14 with the following claims:

- cl
1. A chip electronic component comprising:  
a body of the chip electronic component having outer peripheral surfaces including an upper surface, a lower surface and a pair of side surfaces;  
an electronic component element having electrodes and defining part of said body of the chip electronic component; and

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